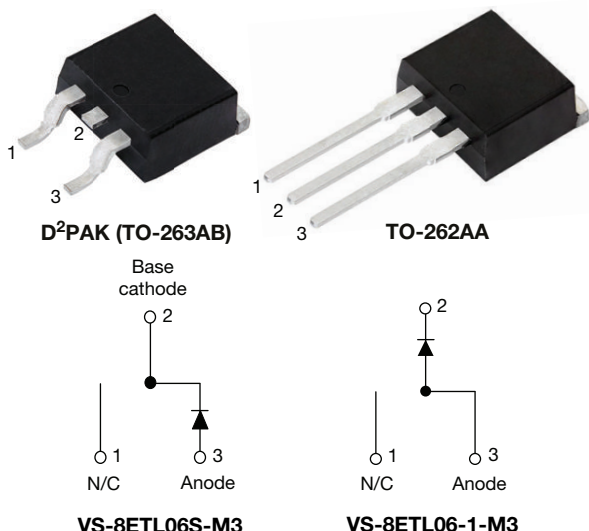


# Ultralow $V_F$ Hyperfast Rectifier for Discontinuous Mode PFC, 8 A FRED Pt®



## FEATURES

- Benchmark ultralow forward voltage drop
- Hyperfast recovery time
- Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



## DESCRIPTION

State of the art, ultralow  $V_F$ , soft-switching hyperfast rectifiers optimized for discontinuous (critical) mode (DCM) power factor correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

## APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units and DVD AC/DC power supplies.

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	8 A
$V_R$	600 V
$V_F$ at $I_F$	0.81 V
$t_{rr}$ typ.	60 ns
$T_J$ max.	175 °C
Package	D <sup>2</sup> PAK (TO-263AB), TO-262AA
Circuit configuration	Single

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 160$ °C	8	A
Non-repetitive peak surge current	$I_{FSM}$	$T_J = 25$ °C	175	
Peak repetitive forward current	$I_{FM}$		16	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-65 to +175	°C

## ELECTRICAL SPECIFICATIONS ( $T_J = 25$ °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100$ $\mu$ A	600	-	-	V
Forward voltage	$V_F$	$I_F = 8$ A	-	0.96	1.05	
		$I_F = 8$ A, $T_J = 150$ °C	-	0.81	0.86	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	0.05	5	$\mu$ A
		$T_J = 150$ °C, $V_R = V_R$ rated	-	20	100	
Junction capacitance	$C_T$	$V_R = 600$ V	-	17	-	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8.0	-	nH

**DYNAMIC RECOVERY CHARACTERISTICS** ( $T_C = 25\text{ }^{\circ}\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1\text{ A}$ , $dI_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	60	100	ns
		$I_F = 8\text{ A}$ , $dI_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	150	250	
		$T_J = 25\text{ }^{\circ}\text{C}$	-	170	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	250	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	15	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	20	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	1.3	-	$\mu\text{C}$
		$T_J = 125\text{ }^{\circ}\text{C}$	-	2.6	-	

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$		-65	-	175	$^{\circ}\text{C}$
Thermal resistance, junction to case per leg	$R_{thJC}$		-	1.4	2	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction to ambient per leg	$R_{thJA}$	Typical socket mount	-	-	70	
Thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth, and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style D <sup>2</sup> PAK (TO-263AB)	8ETL06S			
		Case style TO-262	8ETL06-1			

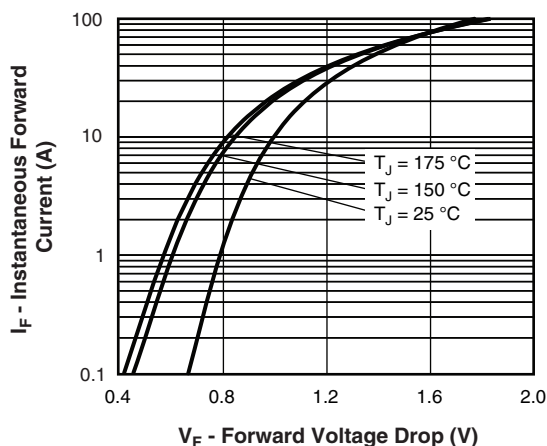


Fig. 1 - Typical Forward Voltage Drop Characteristics

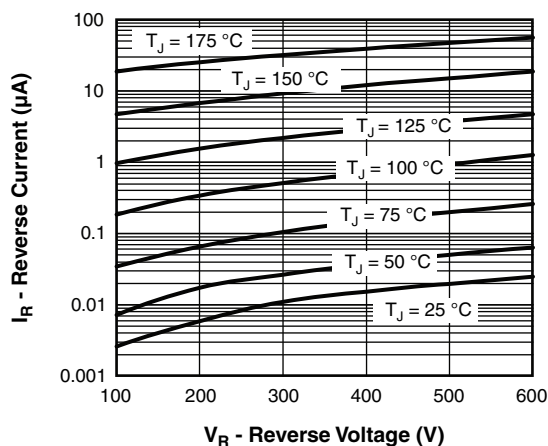


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

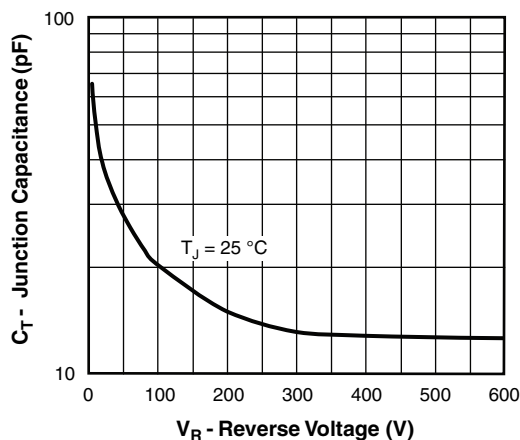


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

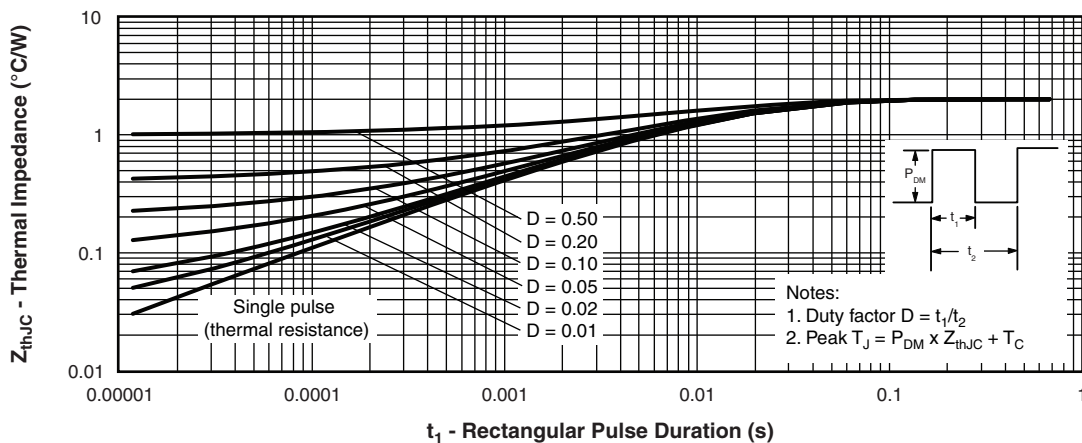
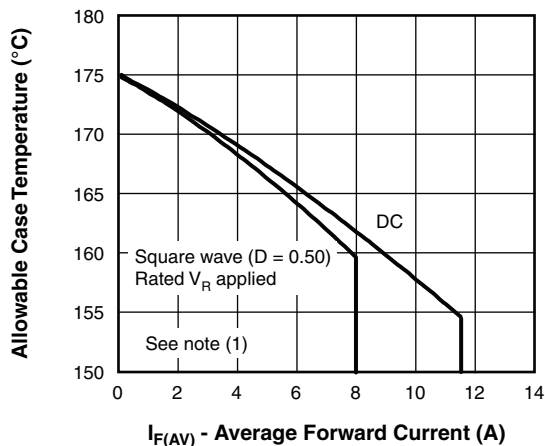

Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

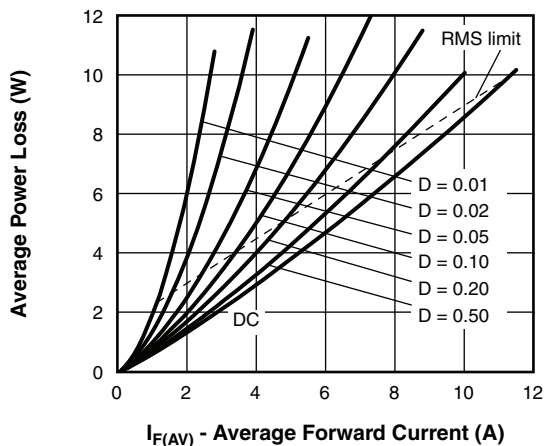
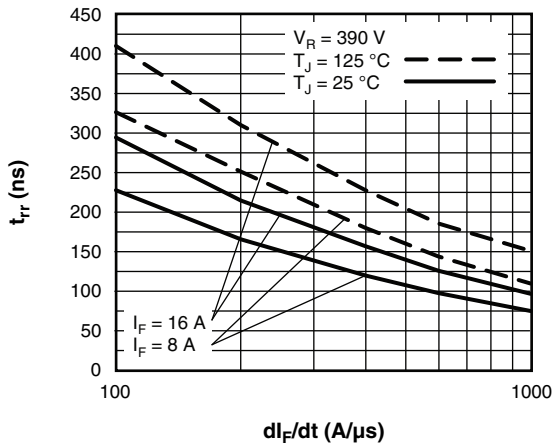
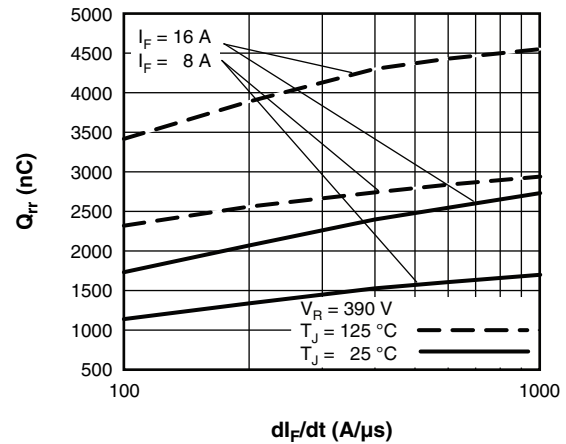


Fig. 6 - Forward Power Loss Characteristics


Fig. 7 - Typical Reverse Recovery Time vs.  $di_F/dt$ 

Fig. 8 - Typical Stored Charge vs.  $di_F/dt$ 

#### Note

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;  
 $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);  
 $P_{dREV}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = rated  $V_R$

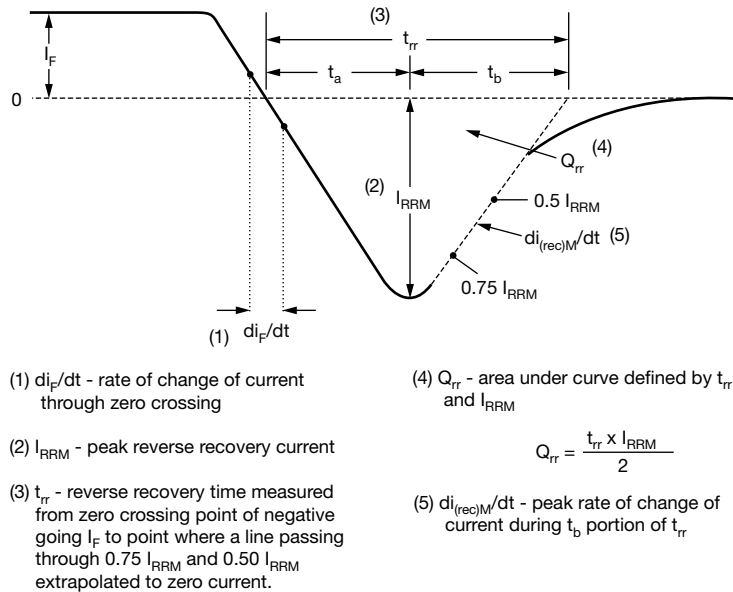


Fig. 9 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	VS-	8	E	T	L	06	S	TRL	-M3
	1	2	3	4	5	6	7	8	9
1	Vishay Semiconductors product								
2	Current rating (8 A)								
3	E = single								
4	T = TO-220, D <sup>2</sup> PAK (TO-263AB)								
5	L = ultralow V <sub>F</sub> hyperfast recovery								
6	Voltage rating (06 = 600 V)								
7	• S = D <sup>2</sup> PAK (TO-263AB) • -1 = TO-262AA								
8	• None = tube (50 pieces) • TRL = tape and reel (left oriented, for D <sup>2</sup> PAK (TO-263AB) package) • TRR = tape and reel (right oriented, for D <sup>2</sup> PAK (TO-263AB) package)								
9	Environmental digit: -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free								

**ORDERING INFORMATION** (Example)

PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-8ETL06S-M3	50	Antistatic plastic tubes
VS-8ETL06STRL-M3	800	13" diameter plastic tape and reel
VS-8ETL06STRR-M3	800	13" diameter plastic tape and reel
VS-8ETL06-1-M3	50	Antistatic plastic tubes

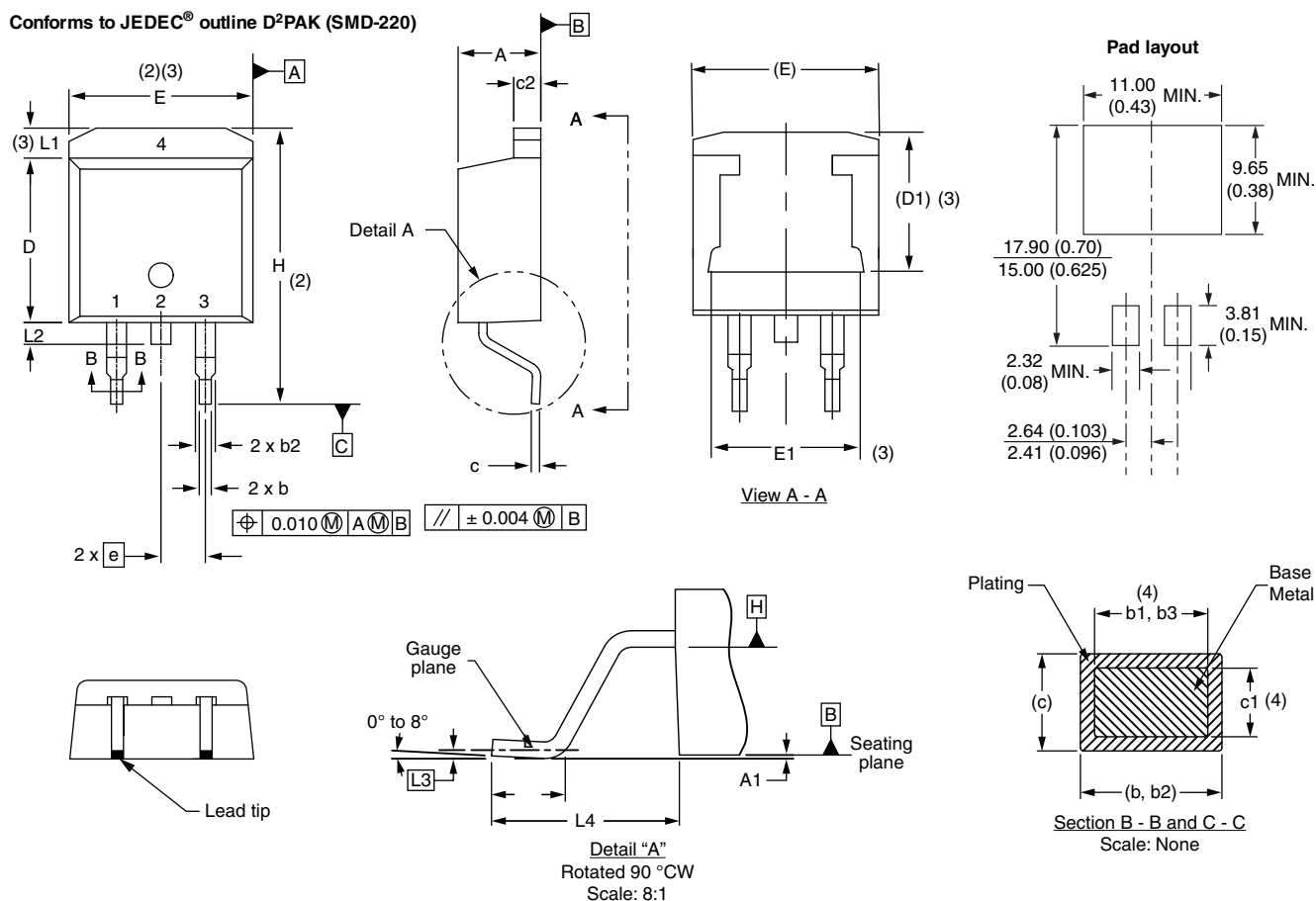
**LINKS TO RELATED DOCUMENTS**

Dimensions	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?96164">www.vishay.com/doc?96164</a>
	TO-262AA	<a href="http://www.vishay.com/doc?96165">www.vishay.com/doc?96165</a>
Part marking information	D <sup>2</sup> PAK (TO-263AB)	<a href="http://www.vishay.com/doc?95444">www.vishay.com/doc?95444</a>
	TO-262AA	<a href="http://www.vishay.com/doc?95443">www.vishay.com/doc?95443</a>
Packaging information		<a href="http://www.vishay.com/doc?96424">www.vishay.com/doc?96424</a>
SPICE model		<a href="http://www.vishay.com/doc?96055">www.vishay.com/doc?96055</a>

# D<sup>2</sup>PAK

**DIMENSIONS** in millimeters and inches

**Conforms to JEDEC® outline D<sup>2</sup>PAK (SMD-220)**



SYMBOL	MILLIMETERS		INCHES		NOTES		SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.			
A	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		e	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070			H	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
c	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25 BSC		0.010 BSC		
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

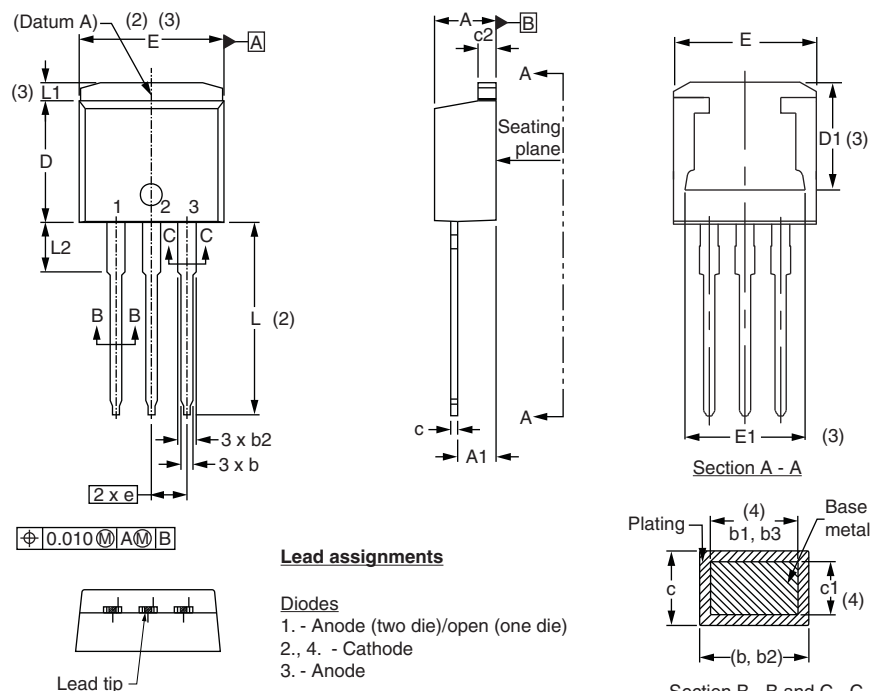
## Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TQ-263AB

### TO-262AA

**DIMENSIONS** in millimeters and inches

Modified JEDEC® outline TO-262



#### Lead assignments

- Diodes**  
 1. - Anode (two die)/open (one die)  
 2., 4. - Cathode  
 3. - Anode

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

#### Notes

- Dimensioning and tolerancing as per ASME Y14.5M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Controlling dimension: inches
- Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)



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